

MCM2708 MCM27A08

1024 X 8 ERASABLE PROM

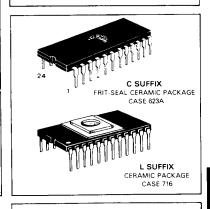
The MCM2708/27A08 is an 8192-bit Erasable and Electrically Reprogrammable PROM designed for system debug usage and similar applications requiring nonvolatile memory that could be reprogrammed periodically. The transparent window on the package allows the memory content to be erased with ultraviolet light. Pin-for-pin mask-programmable ROMs are available for large volume production runs of systems initially using the MCM2708/27A08.

- Organized as 1024 Bytes of 8 Bits
- Static Operation
- Standard Power Supplies of +12 V, +5 V and -5 V
- Maximum Access Time = 300 ns MCM27A08
 450 ns MCM2708
- Low Power Dissipation
- · Chip-Select Input for Memory Expansion
- TTL Compatible
- Three-State Outputs
- Pin Equivalent to the 2708
- Pin-for-Pin Compatible to MCM65308, MCM68308 or 2308 Mask-Programmable ROMs

MOS

(N-CHANNEL, SILICON-GATE)

1024 X 8-BIT UV ERASABLE PROM



PIN CONNECTION DURING READ OR PROGRAM

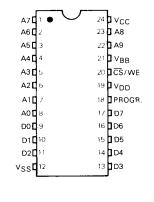
	Pin Number									
Mode	9-11, 13-17	12	18	19	20	21	24			
Read	Dout	VSS	Vss	V _{DD}	VIL	VBB	Vcc			
Program	Din	VSS	Pulsed VIHP	V _{DD}	VIHW	VBB	Vcc			

Rating	Value	Unit	
Operating Temperature	0 to +70	°c	
Storage Temperature	-65 to +125	°C	
V _{DD} with Respect to V _{BB}	+20 to -0.3	Vdc	
V _{CC} and V _{SS} with Respect to V _{BB}	+15 to -0.3	Vdc	
All Input or Output Voltages with Respect to VBB during Read	+15 to -0.3	Vdc	
CS/WE Input with Respect to VBB during Programming	+20 to -0.3	Vdc	
Program Input with Respect to VBB	+35 to -0.3	Vdc	
Power Dissipation	1.8	Watts	

Note 1:

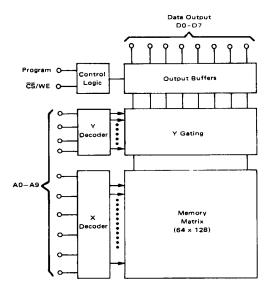
Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

PIN ASSIGNMENT



DS9440 R2/1-79

BLOCK DIAGRAM



DC READ OPERATING CONDITIONS AND CHARACTERISTICS (Full operating voltage and temperature range unless otherwise noted.)

RECOMMENDED DC READ OPERATING CONDITIONS

Parameter	Symbol	Min	Nom	Max	Unit
Supply Voltage	Vcc	4.75	5.0	5.25	Vdc
	V _{DD}	11.4	12	12.6	Vdc
	V _{BB}	-5.25	-5.0	-4.75	Vdc
Input High Voltage	V _{IH}	3.0	_	V _{CC} + 1.0	Vdc
Input Low Voltage	۷۱۲	Vss	_	0.65	Vdc

READ OPERATION DC CHARACTERISTICS

Characteristic Address and CS Input Sink Current Output Leakage Current		Condition	Symbol	Min	Тур	Max	Unit
		$V_{in} = 5.25 \text{ V or } V_{in} = V_{IL}$ $V_{out} = 5.25 \text{ V, } \overline{CS/WE} = 5 \text{ V}$	lin	-	1	10 10	μА
			ILO	_	1		μΑ
VDD Supply Current	1	Worst-Case Supply Currents	¹ DD	_	50	65	mA
V _{CC} Supply Current	(Note 2)	All Inputs High	¹cc	_	6	10	mA
VBB Supply Current	1	CS/WE = 5.0 V, T _A = 0°C	IBB	_	30	45	mA
Output Low Voltage		I _{OL} = 1.6 mA	VOL	_	_	0.45	V
Output High Voltage		I _{OH} = -100 μA	V _{OH} 1	3.7			V
Output High Voltage		I _{OH} = -1.0 mA	√OH2	2.4			
Power Dissipation	(Note 2)	T _A = 70°C	PD	-	_	800	mW

Note 2:

The total power dissipation is specified at 800 mW. It is not calculable by summing the various current (I_{DD}, I_{CC}, and I_{BB}) multiplied by their respective voltages, since current paths exist between the various power supplies and V_{SS}. The I_{DD}, I_{CC}, and I_{BB} currents should be used to determine power supply capacity only.

VBB must be applied prior to VCC and VDD. VBB must also be the last power supply switched off.

AC READ OPERATING CONDITIONS AND CHARACTERISTICS (Full operating voltage and temperature range unless otherwise noted.) (All timing with $t_r = t_f = 20$ ns, Load per Note 3)

		MCM27A08			MCM2708]
Characteristic	Symbol	Min	Тур	Max	Min	Тур	Max	Unit
Address to Output Delay	†AO	_	220	300		280	450	ns
Chip Select to Output Delay	tco		60	120	_	60	120	ns
Data Hold from Address	tDHA	0	-		0		-	ns
Data Hold from Deselection	tDHD	0	-	120	0	_	120	ns

CAPACITANCE (periodically sampled rather than 100% tested.)

Characteristic	Condition	Symbol	Тур	Max	Unit
Input Capacitance (f = 1.0 MHz)	V _{in} = 0 V, T _A = 25°C	C _{in}	4.0	6.0	pF
Output Capacitance (f = 1,0 MHz)	V _{out} = 0 V, T _A = 25°C	C _{out}	8.0	12	ρF

Note 3:
Output Load = 1 TTL Gate and C_L = 100 pF (Includes Jig Capacitance)
Timing Measurement Reference Levels: Inputs: 0.8 V and 2.8 V
Outputs: 0.8 V and 2.4 V

Test Point O

Test Point O

AC TEST LOAD

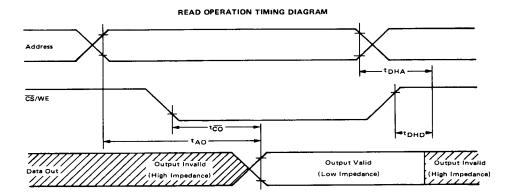
FIGURE 37 K**

MM06150

or Equiv

Includes Jig Capacitance

**For VoH1



DC PROGRAMMING CONDITIONS AND CHARACTERISTICS (Full operating voltage and temperature range unless otherwise noted.)

RECOMMENDED PROGRAMMING OPERATING CONDITIONS

Parameter	Symbol	Min	Nom	Max	Unit
Supply Voltage	Vcc	4.75	5.0	5.25	Vdc
	V _{DD}	11.4	12	12.6	Vdc
	VBB	-5.25	-5.0	-4.75	Vdc
Input High Voltage for All Addresses and Data	VIH	3.0	-	V _{CC} + 1.0	Vdc
Input Low Voltage (except Program)	VIL	Vss	_	0.65	Vdc
CS/WE Input High Voltage (Note 4)	VIHW	11.4	12	12.6	Vdc
Program Pulse Input High Voltage (Note 4)	VIHP	25	-	27	Vdc
Program Pulse Input Low Voltage (Note 5)	VILP	VSS		1.0	Vdc

Note 4: Referenced to VSS.

Note 5: VIHP - VILP = 25 V min.

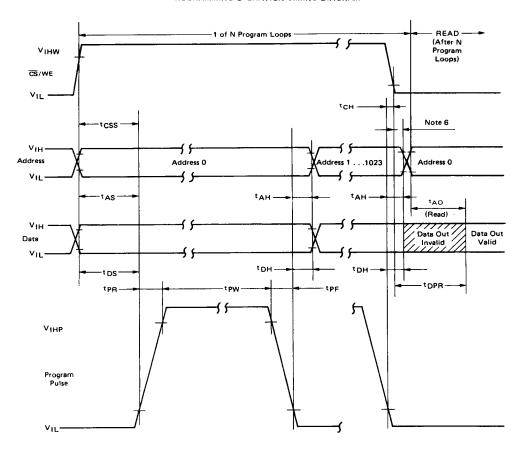
PROGRAMMING OPERATION DC CHARACTERISTICS

Characteristic	Condition	Symbol	Min	Тур	Max	Unit
Address and CS/WE Input Sink Current	V _{in} = 5.25 V	ILI	-	-	10	μAdc
Program Pulse Source Current		liPL	_		3.0	mAdc
Program Pulse Sink Current		IIPH			20	mAdc
V _{DD} Supply Current	Worst-Case Supply Currents	IDD		50	65	mAdc
V _{CC} Supply Current	All Inputs High	¹cc		6	10	mAdc
VBB Supply current	CS/WE = 5 V, T _A = 0°C	I _{BB}	-	30	45	mAdc

AC PROGRAMMING OPERATING CONDITIONS AND CHARACTERISTICS (Full operating voltage and temperature unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
Address Setup Time	†AS	10	_	μs
CS/WE Setup Time	†css	10		μs
Data Setup Time	t _{DS}	10		μs
Address Hold Time	t _{AH}	1.0		μs
CS/WE Hold Time	[†] CH	0.5	_	μς
Data Hold Time	t DH	1.0	_	μς
Chip Deselect to Output Float Delay	tDF	0	120	ns
Program to Read Delay	^t DPR	_	10	μς
Program Pulse Width	tpw	0.1	1.0	ms
Program Pulse Rise Time	t PR	0.5	2.0	μs
Program Pulse Fall Time	tpF	0.5	2.0	μς

PROGRAMMING OPERATION TIMING DIAGRAM



Note 6: The CS/WE transition must occur after the Program Pulse transition and before the Address Transition.

PROGRAMMING INSTRUCTIONS

After the completion of an ERASE operation, every bit in the device is in the "1" state (represented by Output High). Data are entered by programming zeros (Output Low) into the required bits. The words are addressed the same way as in the READ operation. A programmed "0" can only be changed to a "1" by ultraviolet light erasure.

To set the memory up for programming mode, the $\overline{\text{CS/WE}}$ input (Pin 20) should be raised to +12 V. Programming data is entered in 8-bit words through the data output terminals (D0 to D7).

Logic levels for the data lines and addresses and the supply voltages (V_{CC}, V_{DD}, V_{BB}) are the same as for the READ operation.

After address and data setup one program pulse per address is applied to the program input (Pin 18). A program loop is a full pass through all addresses. Total programming time, $T_{Ptotal} = N \times t_{PW} \ge 100 \text{ ms}$. The required number of program loops (N) is a function of the program pulse width (tp_W), where: 0.1 ms ≤ tp_W ≤ 1.0 ms; correspondingly N is: $100 \le N \le 1000$. There must be N successive loops through all 1024 addresses. It is not permitted to apply more than one program pulse in succession to the same address (i.e., N program pulses to an address and then change to the next address to be programmed). At the end of a program sequence the $\overline{\text{CS}}/\text{WE}$ falling edge transition must occur before the first address transition, when changing from a PROGRAM to a READ cycle. The program pin (Pin 18) should be pulled down to V_{ILP} with an active device, because this pin sources a small amount of current (IpL) when CS/WE is at VIHW (12 V) and the program pulse is at VILP.

EXAMPLES FOR PROGRAMMING

Always use the $T_{Ptotal} = N \times t_{PW} \ge 100$ ms relationship.

 All 8192 bits should be programmed with a 0.2 ms program pulse width.

The minimum number of program loops:

$$N = \frac{T_{Ptotal}}{t_{PW}} = \frac{100 \text{ ms}}{0.2 \text{ ms}} = 500 \text{ . One program loop}$$

consists of words 0 to 1023.

- 2. Words 0 to 200 and 300 to 700 are to be programmed. All other bits are "don't care". The program pulse width is 0.5 ms. The minimum number of program loops, $N = \frac{100}{0.5} = 200$. One program loop consists of words 0 to 1023. The data entered into the "don't care" bits should be all 1s.
- 3. Same requirements as example 2, but the EPROM is now to be updated to include data for words 850 to 880. The minimum number of program loops is the same as in the previous example, N = 200. One program loop consists of words 0 to 1023. The data entered into the "don't care" bits should be all 1s. Addresses 0 to 200 and 300 to 700 must be reprogrammed with their original data pattern.

ERASING INSTRUCTIONS

The MCM2708/27A08 can be erased by exposure to high intensity shortwave ultraviolet light, with a wavelength of 2537 Å. The recommended integrated dose (i.e., UV-intensity x exposure time) is 12.5 Ws/cm². As an example, using the "Model 30-000" UV-Eraser (Turner Designs, Mountain View, CA94043) the ERASE-time is 30 minutes. The lamps should be used without shortwave filters and the MCM2708/27A08 should be positioned about one inch away from the UV-tubes.